REMARKS

The specification has been amended to correct typographical errors. The present amendments are not considered or intended to be a narrowing amendment surrendering any equivalents.

Entry and consideration of this Amendment is respectfully requested.

Respectfully submitted,

SUGHRUE MION, PLLC 2100 Pennsylvania Avenue, N.W. Washington, D.C. 20037-3213 Telephone: (202) 293-7060 Facsimile: (202) 293-7860

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J. Frank Osha

Registration No. 24,625

APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION:

The specification is changed as follows:

Page 4, paragraph bridging pages 4-5:

In the present invention the infrared absorption spectrum of a sample is measured according to the following process. First, the sample is subjected to hot pressing at a temperature about 30 to 50°C higher than the melting point of a major component resin contained in the sample (for example about 200°C if the major component resin is a polypropylene resin) for three minutes and then subjected to cold pressing at 30°C for five minutes, to form a film having a thickness of 30 to 80 imum. The film thus obtained is loaded on an infrared spectrometer (for example FT-IR spectrometer Model 1600 manufactured by PERKIN ELMER CO., LTD.) for measurement of its infrared absorption spectrum.

Page 7, first paragraph:

The thickness of the non-foamed surface layer is not particularly limited as long as the surface of the obtained foamed polyolefin resin sheet smoothness and may be determined depending on the application of the sheet or the like. The thickness of the non-foamed surface layer is usually not less than 1 imum, preferably not less than 10 imum, more preferably not less than 50 imum, from the viewpoint of sheet rigidity. From the viewpoint of lightweight property, the non-foamed surface layer is preferably not so thick.

Page 27, second paragraph:

Infrared absorption spectrum

A resin for forming a surface layer of a foamed sheet was hot-pressed at 200°C for three minutes, then subjected to a cold press at 30°C for five minutes, to yield a film having a thickness of 60 imum. This film was loaded on FT-IR spectrometer (model: 1600, manufactured by PERKIN ELMER CO., LTD.) to measure its infrared absorption spectrum.

Page 35, first full paragraph:

Foamed polyolefin resin sheet (12) obtained by the process described above and a film (13) which was either a saponified ethylene-vinyl ester copolymer (EVOH) film (trade name: EVAL EF-E FILM, produced by KURARE CO., LTD., thickness: 15 im im) or a non-stretched polypropylene film (CPP) (trade name: TOYOBO "PAILENE" FILM-CT P1146, produced by TOYOBOSEKI CO., LTD., thickness: 80 im im), were passed together between a pair of nip rolls (14) adjusted to 120°C at a line speed of 1 m/min, while hot air was applied to the nip portion from an air-knife (16) connected to a hot air generator (15) so that the temperature of hot air at the nip roll section assumed 190°C. Thus, there was obtained a laminate (17) having the foamed polyolefin resin sheet thermolaminated with the ethylene-vinyl ester copolymer film.

Page 39, paragraph bridging pages 39 and 40:

As the non-foamed surface layer forming material there was used a resin mixture prepared by blending 100 parts by weight of polypropylene (trade name: PF814, produced by MONTEL CO., melting point: 159.0°C, crystallization temperature: 130.1°C, MFR: 2.2 g/10 min (230°C)) with 100 parts by weight of resin recycled from scrap of a foamed polyolefin resin sheet formed by laminating a multi-layered foamed sheet comprising non-foamed surface layer

and foamed layer formed from a polypropylene resin and arranged into a structure of non-foamed surface layer (80 imμm)/foamed layer (2200 imμm)/non-foamed surface layer (80 imμm) with a 100 imμm-thick multi-layered film comprising non-stretched polypropylene (hereinafter abbreviated as "CCP") layer (25 imμm)/maleic anhydride-modified polypropylene layer (10 im)μm)/saponified ethylene-vinyl ester copolymer layer (30 imμm)/maleic anhydride-modified polypropylene layer (10 imμm)/CCP layer (25 imμm).